

Notice of References Cited	Application/Control No. 09/851,313		Applicant(s)/Patent Under Reexamination USAMI, TATSUYA	
	Examiner Julio J. Maldonado		Art Unit 2823	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,054,379	04-2000	Yau et al.	438/623
*	B	US-6,333,257	12-2001	Aoi, Nobuo	438/626
*	C	US-6,218,317	04-2001	Allada et al.	438/780
X	D	US-			
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	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Wolf et al., Silicon Processing for the VLSI Era, Volume 1, PProcess technology, 1986 by Lattice Press, pages 168-174
*	V	Chen et al., Effects of Slurry formulations on chemical-mechanical polishing of low dielectric constant polysiloxanes: hydrido-organo siloxane and methyl silsesquioxane; J. Vac. Sci. Technol. B 18(1), Jan/Feb 2000, pages 201-207
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	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.